

	U	I	Document ID	Issue Date	Pages	Title	Current OP	Current XRef	+
2	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 20040102001 A1	20040527	6	Three layer aluminum deposition process for high aspect ratio CL contacts	438/239	438/256; 438/688	
3	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 20040099965 A1	20040527	26	Integrated circuits having self-aligned metal 1/1 contact structures			
4	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 20040098208 A1	20040520	24	Methods, systems and computer programs for deconvolving the spectral	702/32		
5	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 20040094778 A1	20040520	73	Semiconductor device and semiconductor memory device provided with internal	257/202		
6	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 20040087098 A1	20040506	14	MIM AND METAL RESISTOR FORMATION AT CU BEOL USING ONLY ONE EXTRA	438/381		
7	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 20040073105 A1	20040415	15	Cardiac diagnostics using wall motion and perfusion cardiac MRI imaging and	600/410		
8	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 20040072439 A1	20040415	16	Chemical mechanical polishing composition and process	438/694		
9	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 20040042387 A1	20040304	178	Communication system with multicarrier telephony transport	370/206		
10	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 20040042292 A1	20040304	26	Semiconductor device	365/202		
11	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 20040041263 A1	20040304	31	Integrated circuit with modified metal features and method of fabrication	257/752		
12	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 20040029374 A1	20040212	6	Compact semiconductor structure and method for producing the same	438/618	438/624; 438/637;	